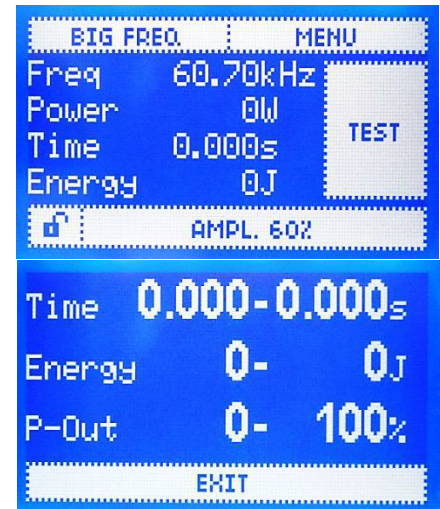
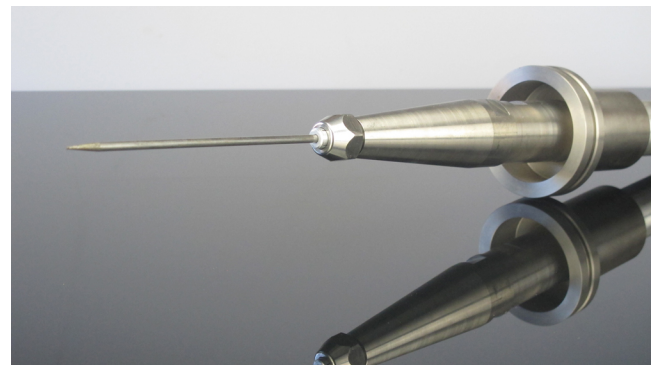


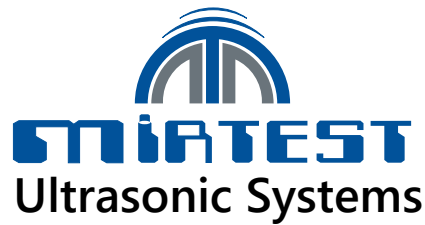
Ultrasonic Grinding, Lapping, Drilling, Drawing Die Procession



FEATURES

- Time & Energy Mode
- Amplitude Control Automatic
- Frequency Tuning
- Touch Screen & Rotary Encoder
- Ultrasonic Load Meter Scale
- Over Load
- No Load
- Short Circuit
- Overtemperature





Ultrasonic Grinding, Lapping, Drilling, Drawing Die Procession

Ultrasonic Grinding

Ultrasonic grinding is suitable for industries where difficult materials (ceramics, glass, hart metal) have to be machined.

Ultrasonic Lapping

Ultrasonic lapping place in production of complex geometrically workpieces out of recalcitrant materials.

Ultrasonic Drilling

Ultrasonic drilling don't uses rotation for drilling, but rather the piezoelectric effect. In this way, contact pressure, weight of the drill and energy consumption can be significantly reduced.

Drilling by ultrasonic is ideal for medical and dental industry. It also can be used for rotary cutting unsuitable materials such as ceramics or glass.

Ultrasonic Drawing Die Procession

Offers the possibility for post processing of diamond drawing dies.

Technical Data

Power: Up to 2000 Watt

Frequencies: 20 - 60 kHz

Materials: Massive special titanium alloy, spec. stainless steel

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